



US00D485277S

(12) **United States Design Patent**  
**Huang**

(10) **Patent No.:** **US D485,277 S**

(45) **Date of Patent:** **\*\* Jan. 13, 2004**

(54) **COMPUTER MAINFRAME FRONT PANEL**

D464,357 S \* 10/2002 Chien et al. .... D14/444

(75) Inventor: **Hui-Chia Huang**, Taipei Hsien (TW)

\* cited by examiner

(73) Assignee: **Thermaltake Technology Co., Ltd.**,  
Taipei Hsien (TW)

*Primary Examiner*—Freda Nunn

(74) *Attorney, Agent, or Firm*—Rosenberg, Klein & Lee

(\*\*) Term: **14 Years**

(57) **CLAIM**

(21) Appl. No.: **29/174,548**

The ornamental design for a computer mainframe front panel, as shown and described.

(22) Filed: **Jan. 22, 2003**

(30) **Foreign Application Priority Data**

**DESCRIPTION**

Dec. 27, 2002 (TW) ..... 91307614

FIG. 1 is a top, front and right side perspective view of a computer mainframe front panel showing my new design;

(51) **LOC (7) Cl.** ..... **14-02**

FIG. 2 is a front elevational view thereof;

(52) **U.S. Cl.** ..... **D14/444**

FIG. 3 is a rear elevational view thereof;

(58) **Field of Search** ..... D14/441-446;  
D13/162, 184, 199; 312/223.2; 361/690-696

FIG. 4 is a left side view thereof;

FIG. 5 is a right side view thereof;

(56) **References Cited**

FIG. 6 is a top plan view thereof; and,

FIG. 7 is a bottom plan view thereof.

**U.S. PATENT DOCUMENTS**

D454,133 S \* 3/2002 Yang ..... D14/441

**1 Claim, 5 Drawing Sheets**



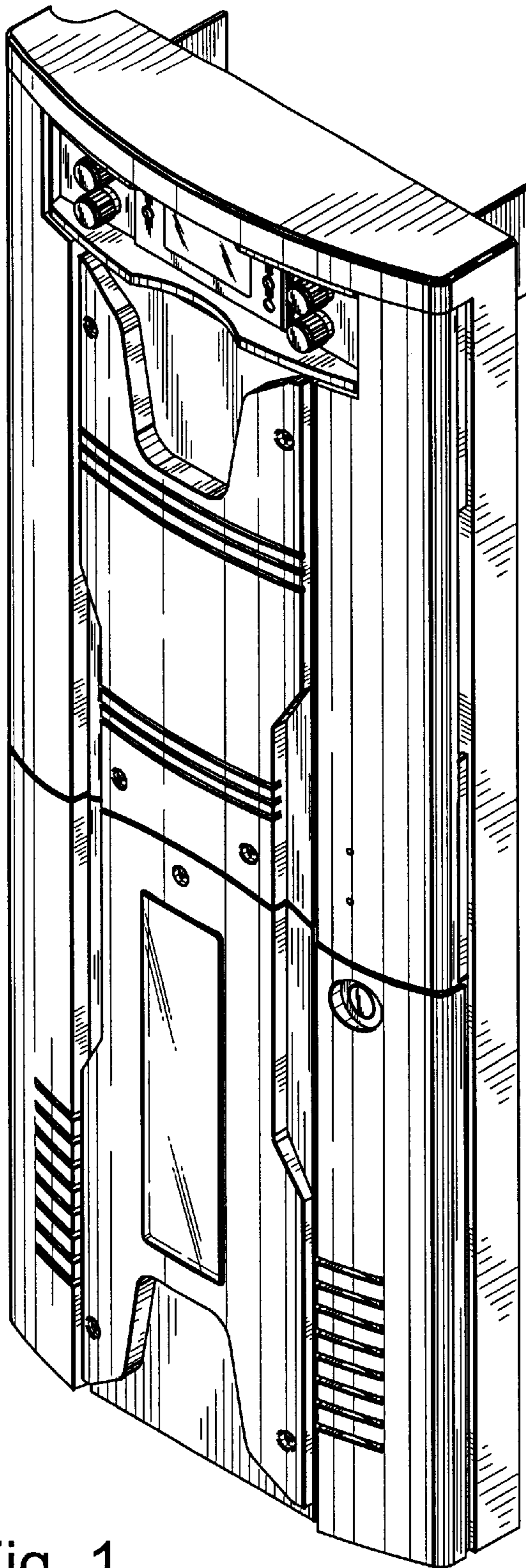


Fig. 1

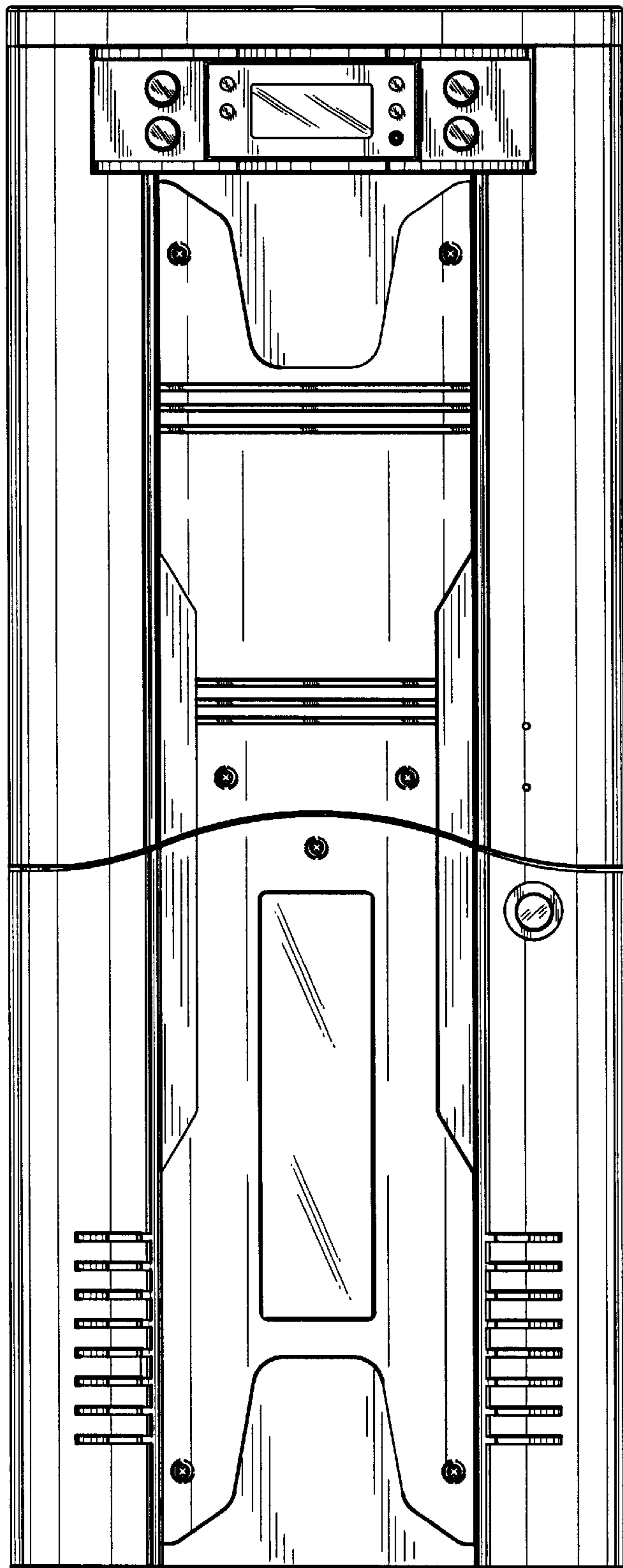


Fig. 2

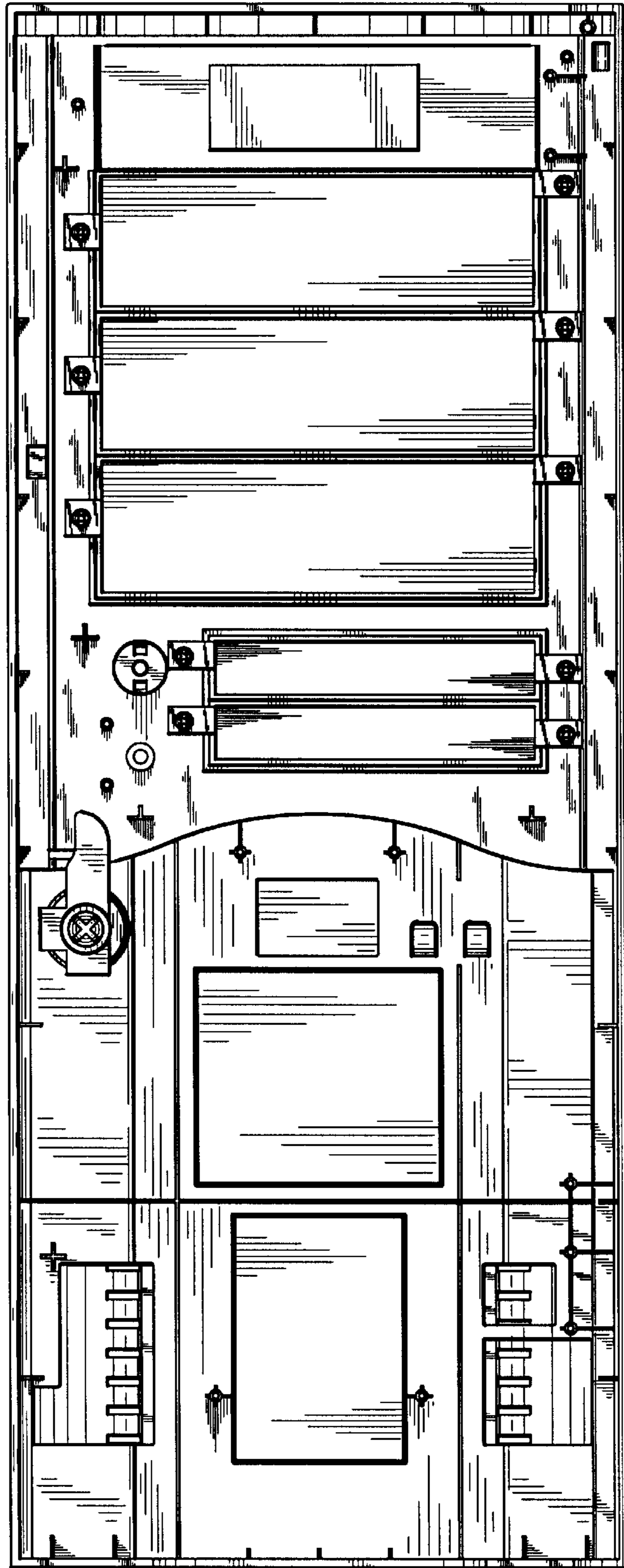


Fig. 3

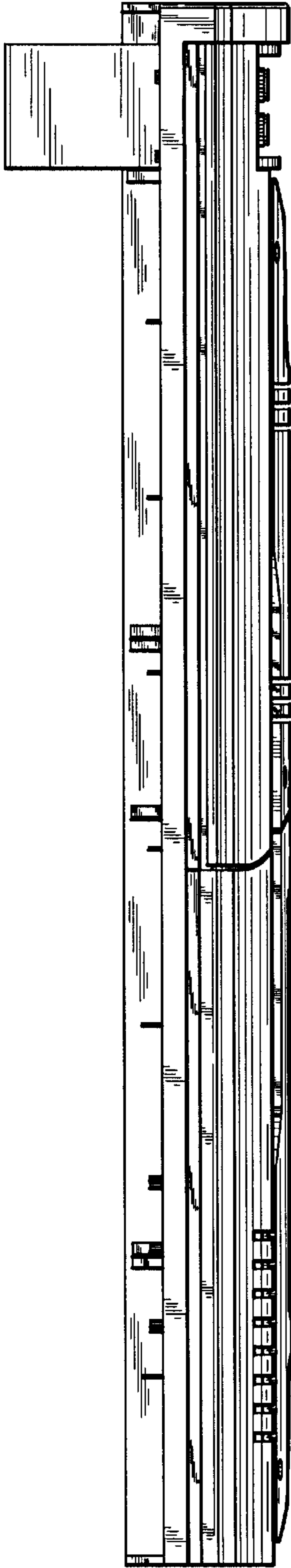


Fig. 4

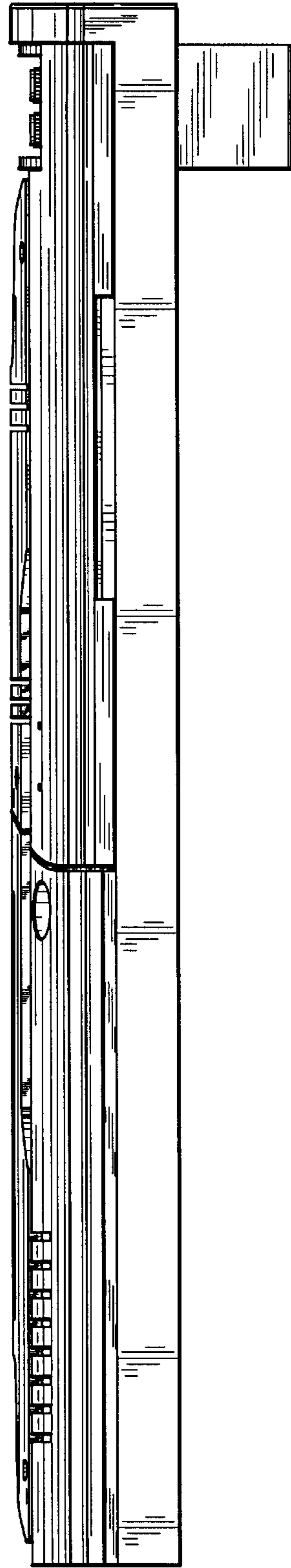


Fig. 5

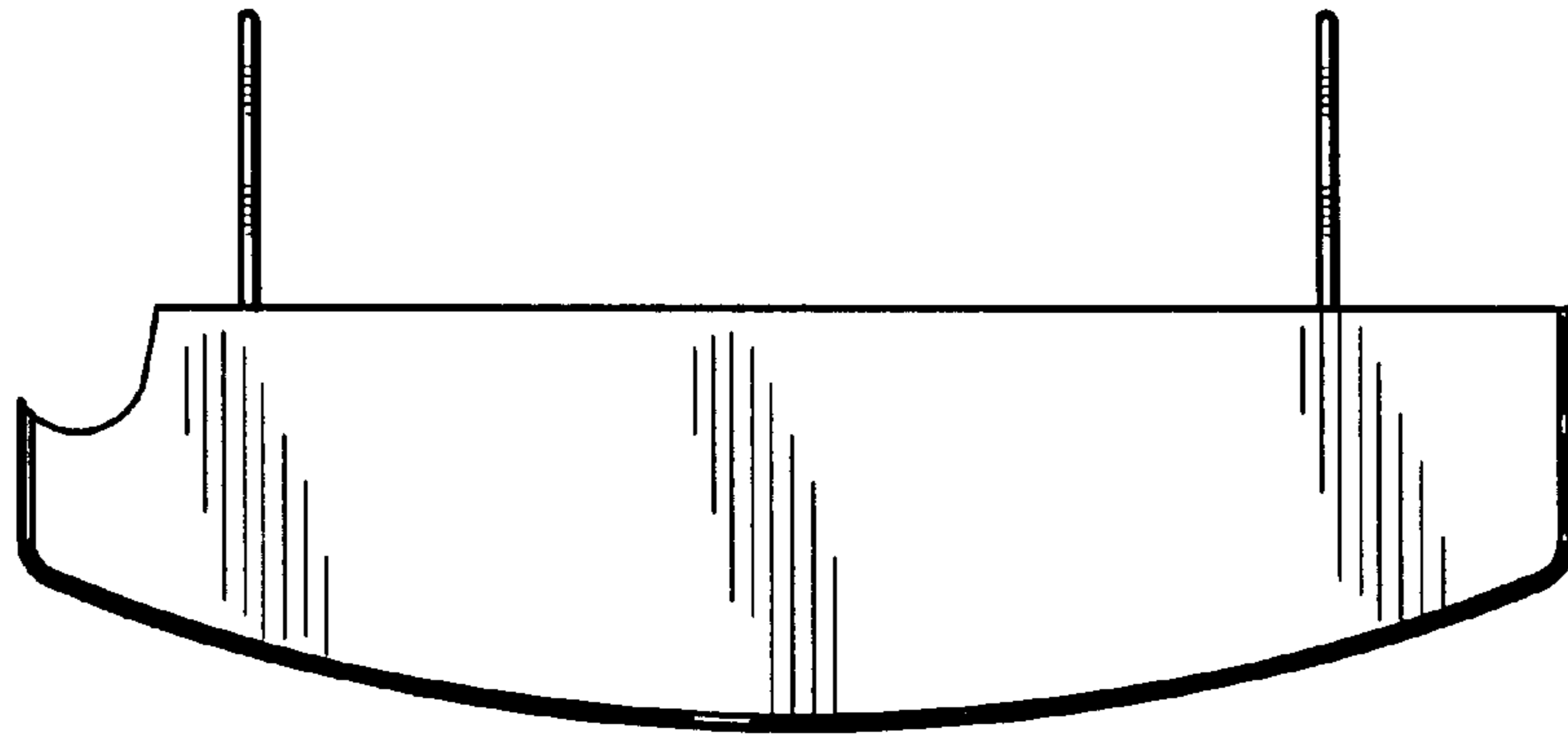


Fig. 6

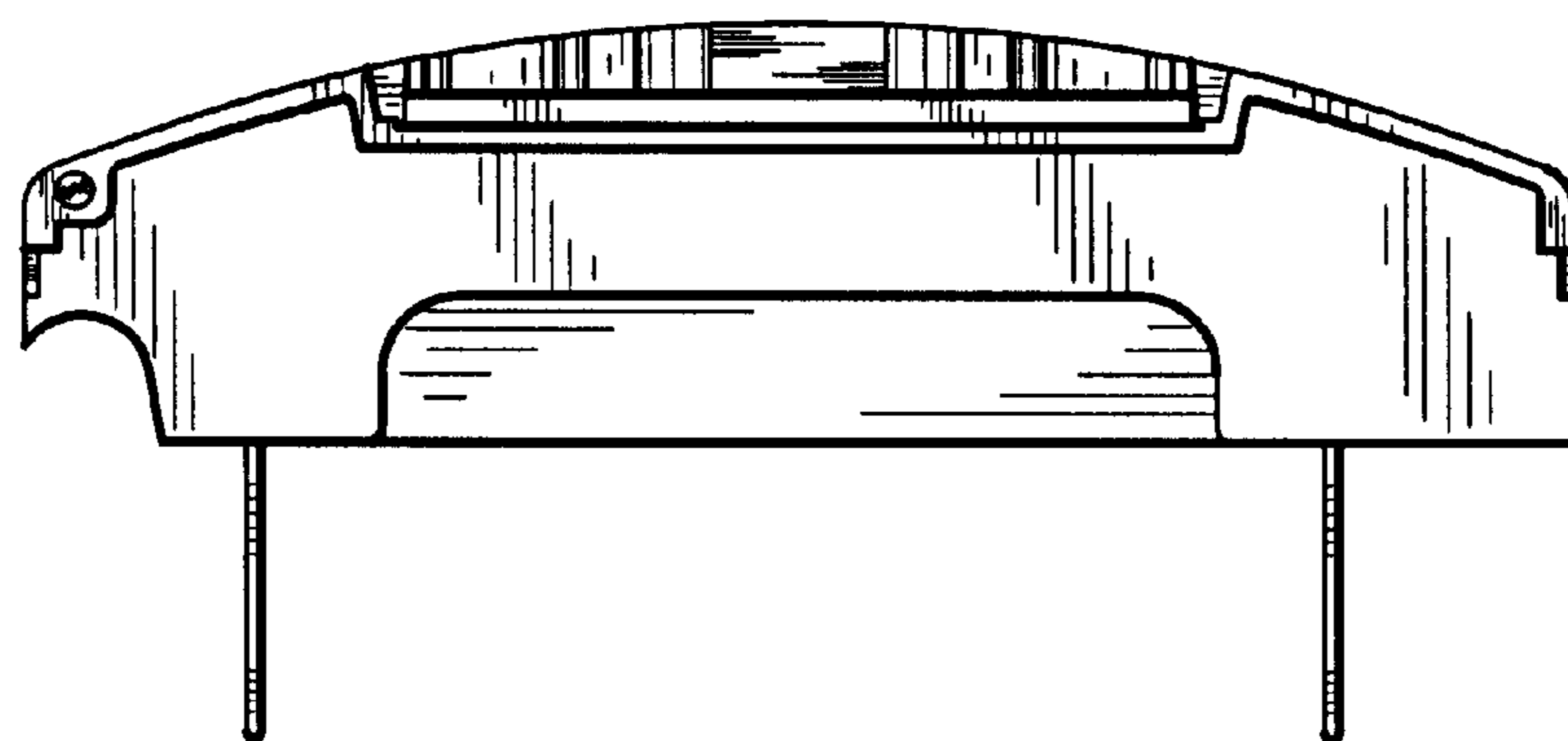


Fig. 7